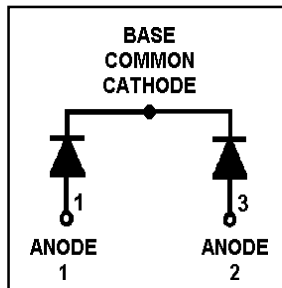


### Features

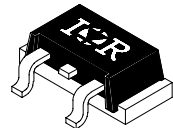
- Reduced RFI and EMI
- Reduced Snubbing
- Extensive Characterization of Recovery Parameters



|  |
|--|
| $V_R = 600V$   |
| $V_F(\text{typ.})^{\textcircled{3}} = 1.2V$                        |
| $I_F(\text{AV}) = 70A$   |
| $Q_{rr}(\text{typ.}) = 210nC$                                      |
| $I_{RRM}(\text{typ.}) = 6A$  |
| $t_{rr}(\text{typ.}) = 30ns$                                       |
| $di_{(\text{rec})}/dt(\text{typ.})^{\textcircled{3}} = 180A/\mu s$ |

### Description

HEXFRED™ diodes are optimized to reduce losses and EMI/RFI in high frequency power conditioning systems. An extensive characterization of the recovery behavior for different values of current, temperature and di/dt simplifies the calculations of losses in the operating conditions. The softness of the recovery eliminates the need for a snubber in most applications. These devices are ideally suited for power converters, motors drives and other applications where switching losses are significant portion of the total losses.



**SLD-61-8**

### Absolute Maximum Ratings (per Leg)

|                           | Parameter                          | Max.                              | Units      |
|---------------------------|------------------------------------|-----------------------------------|------------|
| $V_R$                     | Cathode-to-Anode Voltage           | 600                               | V          |
| $I_F @ T_C = 25^\circ C$  | Continuous Forward Current         | 56                                | A          |
| $I_F @ T_C = 100^\circ C$ | Continuous Forward Current         | 27                                |            |
| $I_{FSM}$                 | Single Pulse Forward Current ①     | 200                               |            |
| $E_{AS}$                  | Non-Repetitive Avalanche Energy ②  | 220                               | $\mu J$    |
| $P_D @ T_C = 25^\circ C$  | Maximum Power Dissipation          | 150                               | W          |
| $P_D @ T_C = 100^\circ C$ | Maximum Power Dissipation          | 59                                |            |
| $T_J$                     | Operating Junction and             | -55 to +150                       | $^\circ C$ |
| $T_{STG}$                 | Storage Temperature Range          |                                   |            |
|                           | Soldering Temperature, for 10 sec. | 300 (0.063 in. (1.6mm) from case) |            |

### Thermal - Mechanical Characteristics

|            | Parameter                               | Min. | Typ.       | Max. | Units        |
|------------|---|------|------------|------|--------------|
| $R_{thJC}$ | Junction-to-Case, Single Leg Conducting | —    | —          | 0.85 | $^\circ C/W$ |
|            | Junction-to-Case, Both Legs Conducting  | —    | —          | 0.42 | $K/W$        |
| Wt         | Weight                                  | —    | 4.3 (0.15) | —    | g (oz)       |

Note: ① Limited by junction temperature

②  $L = 100\mu H$ , duty cycle limited by max  $T_J$

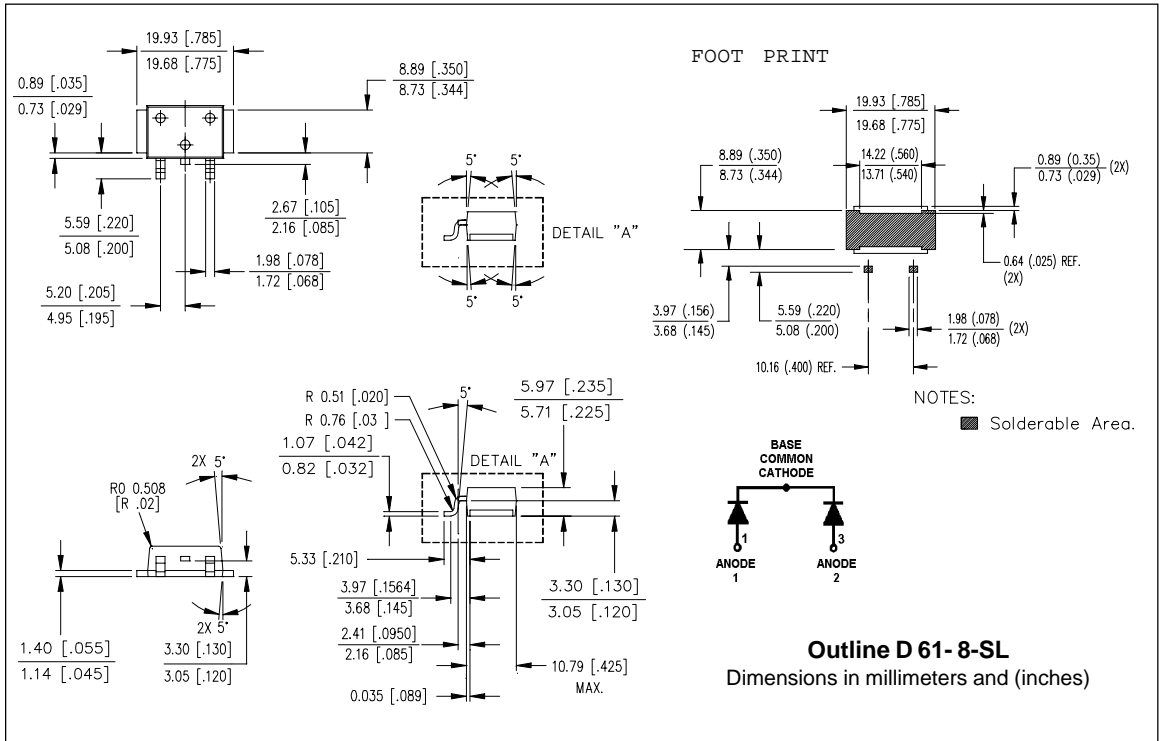
③  $125^\circ C$

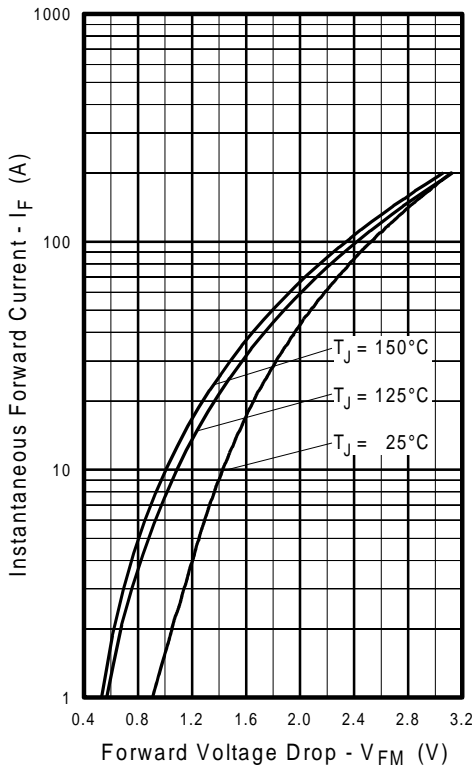
### Electrical Characteristics (per Leg) @ T<sub>J</sub> = 25°C (unless otherwise specified)

| Parameter       | Min. | Typ. | Max. | Units | Test Conditions  |
|-----------------|------|------|------|-------|--|
| V <sub>BR</sub> | 600  | —    | —    | V     | I <sub>R</sub> = 100µA   |
| V <sub>FM</sub> | —    | 1.3  | 1.5  | V     | I <sub>F</sub> = 35A<br>I <sub>F</sub> = 70A<br>I <sub>F</sub> = 35A, T <sub>J</sub> = 125°C |
|                 |      | 1.5  | 1.7  |       |  |
|                 |      | 1.2  | 1.4  |       |  |
| I <sub>RM</sub> | —    | 2.0  | 10   | µA    | V <sub>R</sub> = V <sub>R</sub> Rated<br>T <sub>J</sub> = 125°C, V <sub>R</sub> = 480V       |
|                 |      | 0.50 | 2.0  |       |  |
| C <sub>T</sub>  | —    | 68   | 100  | pF    | V <sub>R</sub> = 200V  |
| L <sub>S</sub>  | —    | 5.5  | —    | nH    | Lead to lead 5mm from package body   |

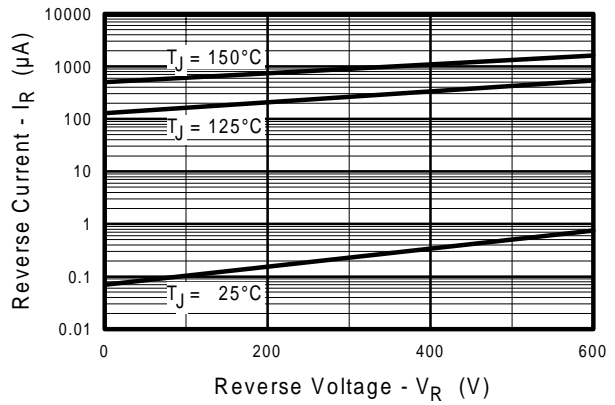
### Dynamic Recovery Characteristics (per Leg) @ T<sub>J</sub> = 25°C (unless otherwise specified)

| Parameter                 | Min. | Typ. | Max. | Units | Test Conditions   |
|---------------------------|------|------|------|-------|---|
| t <sub>rr</sub>           | —    | 30   | —    | ns    | I <sub>F</sub> = 1.0A, di <sub>F</sub> /dt = 200A/µs, V <sub>R</sub> = 30V<br>T <sub>J</sub> = 25°C<br>T <sub>J</sub> = 125°C |
| t <sub>rr1</sub>          | —    | 70   | 110  |       |   |
| t <sub>rr2</sub>          | —    | 115  | 180  |       |   |
| I <sub>RRM1</sub>         | —    | 6.0  | 11   | A     | T <sub>J</sub> = 25°C<br>T <sub>J</sub> = 125°C   |
| I <sub>RRM2</sub>         | —    | 9.0  | 16   |       |   |
| Q <sub>rr1</sub>          | —    | 210  | 580  | nC    | T <sub>J</sub> = 25°C<br>T <sub>J</sub> = 125°C   |
| Q <sub>rr2</sub>          | —    | 520  | 1400 |       |   |
| di <sub>(rec)M</sub> /dt1 | —    | 280  | —    | A/µs  | T <sub>J</sub> = 25°C<br>T <sub>J</sub> = 125°C   |
| di <sub>(rec)M</sub> /dt2 | —    | 180  | —    |       |   |

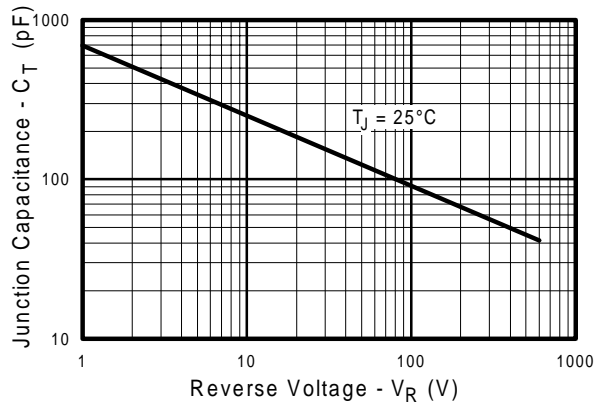




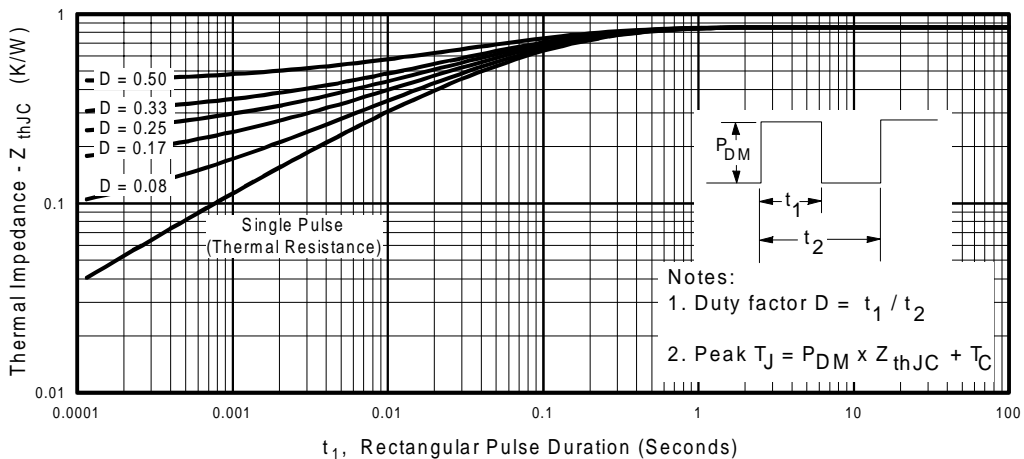
**Fig. 1 - Maximum Forward Voltage Drop vs. Instantaneous Forward Current, (per Leg)**



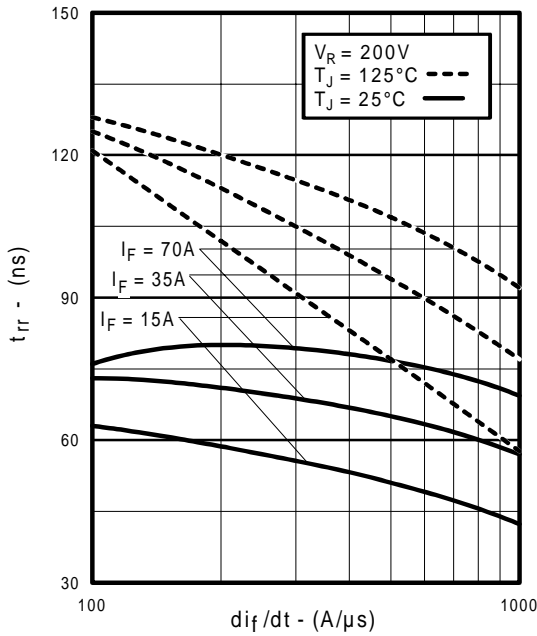
**Fig. 2 - Typical Reverse Current vs. Reverse Voltage, (per Leg)**



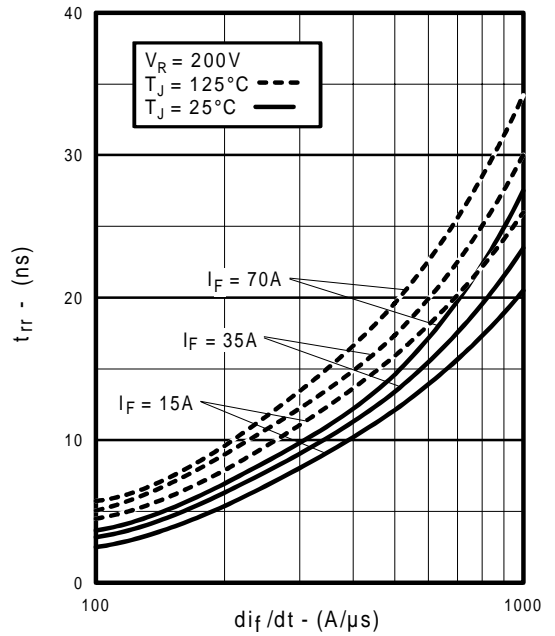
**Fig. 3 - Typical Junction Capacitance vs. Reverse Voltage, (per Leg)**



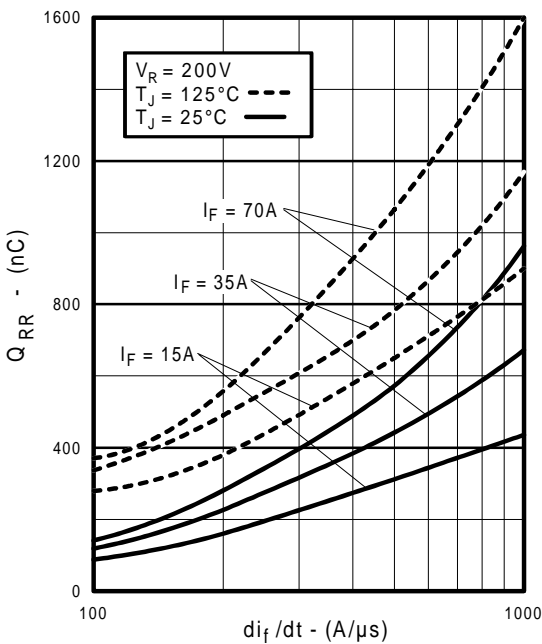
**Fig. 4 - Maximum Thermal Impedance  $Z_{thJC}$  Characteristics, (per Leg)**



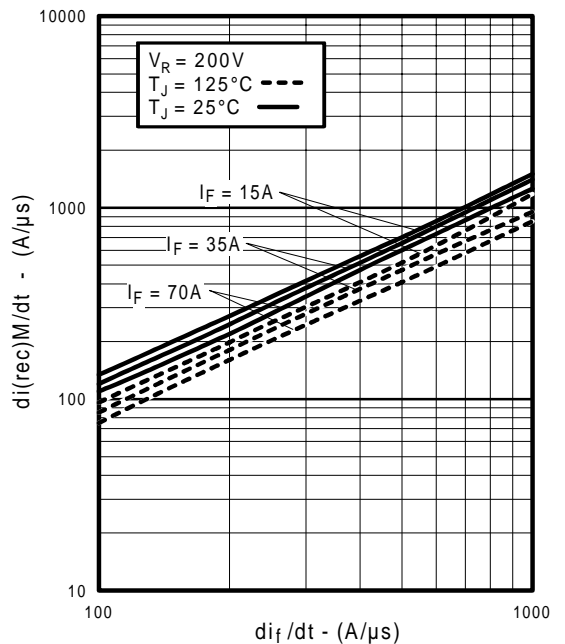
**Fig. 5** - Typical Reverse Recovery vs.  $di_f/dt$ , (per Leg)



**Fig. 6** - Typical Recovery Current vs.  $di_f/dt$ , (per Leg)

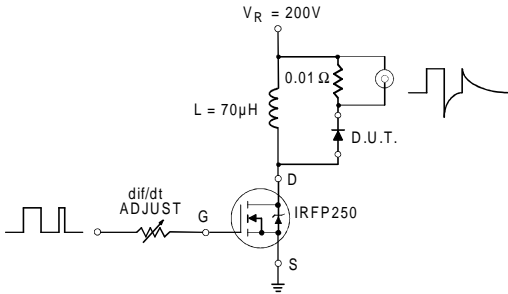


**Fig. 7** - Typical Stored Charge vs.  $di_f/dt$ , (per Leg)

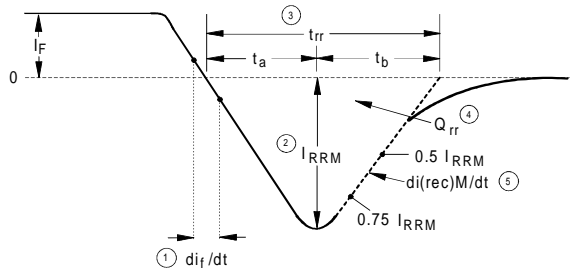


**Fig. 8** - Typical  $di_{(rec)M}/dt$  vs.  $di_f/dt$ , (per Leg)

REVERSE RECOVERY CIRCUIT



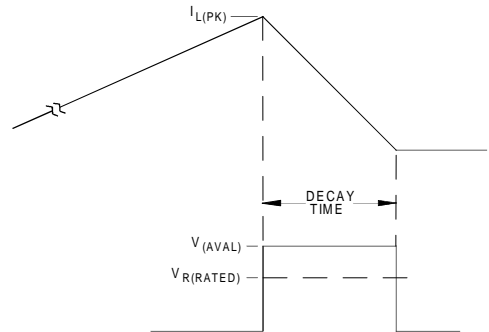
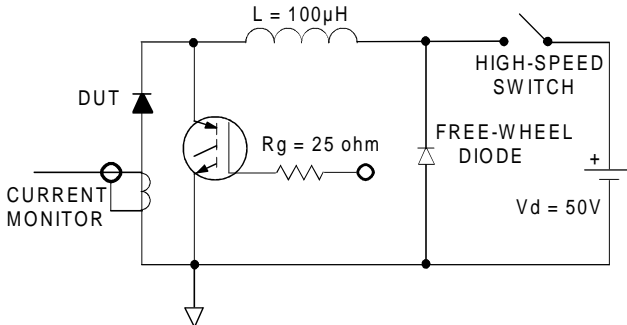
**Fig. 9** - Reverse Recovery Parameter Test Circuit



1.  $di_I/dt$  - Rate of change of current through zero crossing
2.  $I_{RRM}$  - Peak reverse recovery current
3.  $t_{rr}$  - Reverse recovery time measured from zero crossing point of negative going  $I_F$  to point where a line passing through  $0.75 I_{RRM}$  and  $0.5 I_{RRM}$  extrapolated to zero current
4.  $Q_{rr}$  - Area under curve defined by  $t_{rr}$  and  $I_{RRM}$
5.  $di_{(rec)M}/dt$  - Peak rate of change of current during  $t_b$  portion of  $t_{rr}$

$$Q_{rr} = \frac{t_{rr} \times I_{RRM}}{2}$$

**Fig. 10** - Reverse Recovery Waveform and Definitions



**Fig. 11** - Avalanche Test Circuit and Waveforms

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